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**(71) Applicant(s):**

SUMITOMO ELECTRIC INDUSTRIES, LTD. [JP/JP]; 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka 5410041 (JP) (*for all designated states*)

**(72) Inventor(s):**

KURIYAMA, Hiromitsu; c/o SUMITOMO ELECTRIC INDUSTRIES, LTD., 5-33, Kitahama 4-chome, Chuo-ku, Osaka-shi, Osaka 5410041 (JP)

**(74) Agent(s):**

KITANO, Shuhei; K&T IP LAW FIRM, Kitahama 1-Chome Heiwa Bldg. 9F, 1-14, Kitahama 1-chome, Chuo-ku, Osaka-shi, Osaka 5410041 (JP)

**(54) Title (EN):** SENSOR MODULE

**(54) Title (FR):** MODULE DE CAPTEUR

**(54) Title (JA):** センサモジュール

**(57) Abstract:**

**(EN):** This sensor module comprises: a sensor unit; a housing that has an adhesion surface and that accommodates the sensor unit; and a first magnet that is adhered to the housing. The magnetism between the first magnet and an attachment object is stronger than the adhesion between the housing and the first magnet.

**(FR):** Ce module de capteur comprend : une unité de capteur ; un boîtier qui a une surface d'adhérence et qui reçoit l'unité de capteur ; et un premier aimant qui est collé au boîtier. Le magnétisme entre le premier aimant et un objet de fixation est plus fort que l'adhérence entre le boîtier et le premier aimant.

**(JA):** センサモジュールは、センサ部と、接着面を有し、センサ部を收容する筐体と、筐体に接着される第1磁石と、を備える。第1磁石と取り付け対象物との間の磁力は、筐体と第1磁石との接着力よりも強い。

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